Specification of Thermoelectric Module TEC1-12714

Description

The 127 couples, 50 mm × 50 mm size single stage module is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70, designed for superior cooling and heating up to 100 °C requirement. It has higher cooling efficiency than normal type module. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

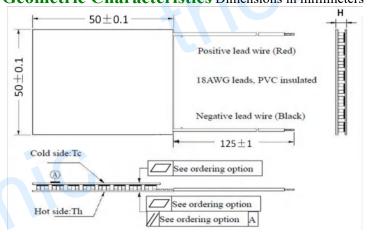
Application

- Food and beverage service refrigerator
- Photonic and medical systems
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
III (C)	21	30	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C) 70		79	Temperature Difference between cold and hot side of the module	
	. 0	. ,	when cooling capacity is zero at cold side	
U _{max} (Voltage)	16.2	17.5	Voltage applied to the module at DT _{max}	
I _{max} (amps)	14	14	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	139.5	150.2	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (ohms)	0.88	0.95	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness	Flatness/	Lead wire length(mm)		
	(mm)	Parallelism (mm)	Standard/Optional length		
TF	0:4.3±0.1	0:0.1/0.1	125±1/Specify		
TF	1:4.3±0.05	1:0.05/0.05	125±1/Specify		
Eg. TF00: Thickness 4.3 ± 0.1 (mm) and Flatness $0.1 / 0.1$ (mm)					

Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217° C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240°C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

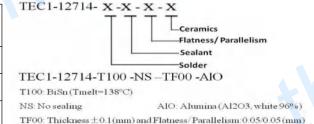
1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

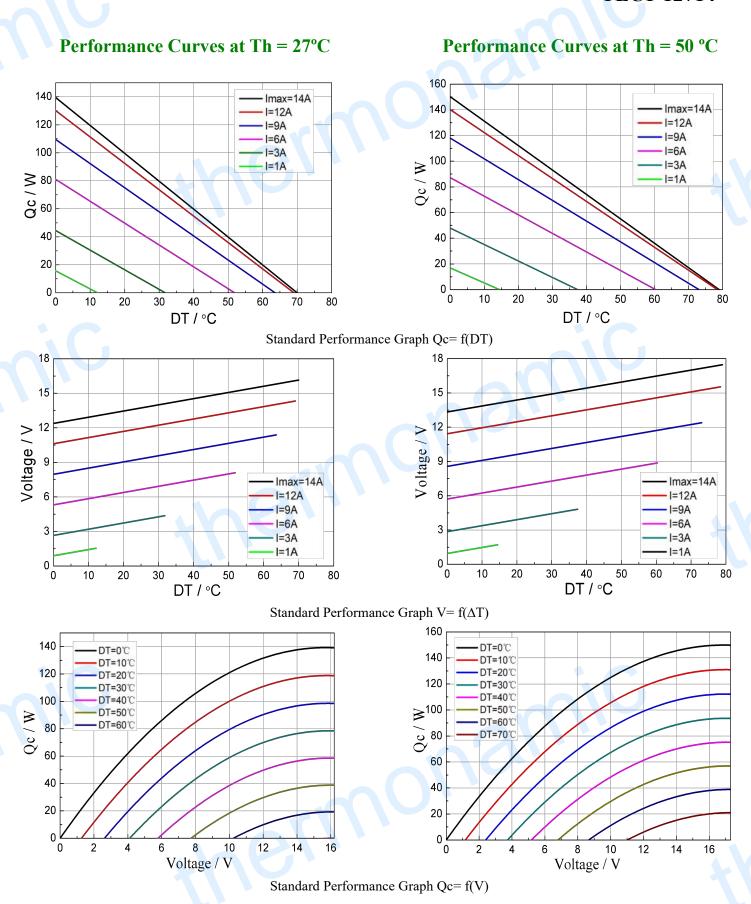
2. Metalized

Naming for the Module



Specification of Thermoelectric Module

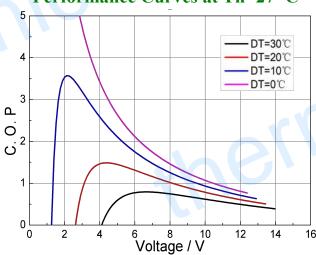
TEC1-12714



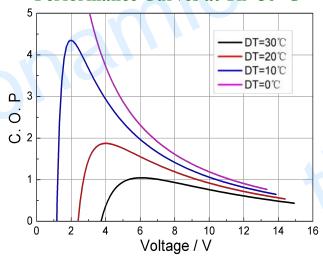
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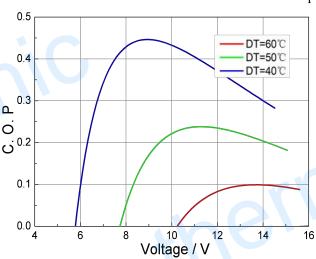


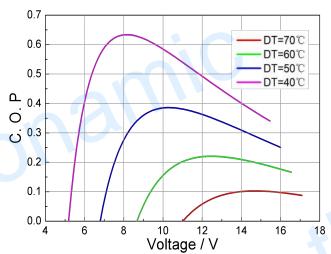


Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- • Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC